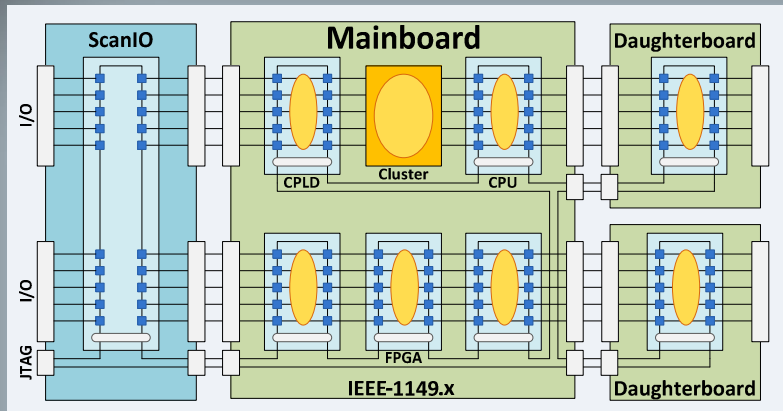


ScanExpress Merge™

CORELIS
An EWA Company

System-Level Interconnect Solution
For ScanExpress Boundary-Scan Tools

Preferred Boundary-Scan Solutions—Acclaimed Technical Support



Features

- Automatically combines board-level test projects for use with system level test generation
- Supports all boundary-scan tests including infrastructure, interconnect, buswire, clusters, memories, and Flash
- Automatically creates connection lists for mated connectors
- Includes built-in support for Corelis ScanIO™, ScanPCI™, and ScanDIMM™ boundary-scan IO modules
- Intuitive step-by-step wizard simplifies the merge process
- Integrates with ScanExpress TPG™ for fast and convenient test development and generation
- Compliant to IEEE standards 1149.1 and 1149.6
- Compatible with Windows XP, Windows Vista, and Windows 7

Benefits

- **Test multiple sub-assemblies** with a single test plan for increased test coverage and convenience
- **Increase overall test coverage** to include connectors between system assemblies
- **Painless integration** of additional boundary-scan IO modules for expanded test coverage
- **Compatible** with the ScanExpress TPG Integrated Development Environment (IDE) for automatic development and generation

Combine Multiple Assembly Test Files

Corelis ScanExpress Merge, a member of the ScanExpress suite of boundary-scan test tools, is a software application designed to import and join test files for multiple independent assemblies and assist in configuration of a combined test procedure.

Using completed ScanExpress TPG test files and module interconnection data, ScanExpress Merge quickly combines combined test plan files for system testing with minimal user effort.

Now boundary-scan tests can be easily extended to test systems that consist of multiple PCBs, multi-chip modules, or coverage extending IO modules—treating them as a single, combined unit for cohesive, complete, and convenient system-level testing.

Applications

- **Hierarchical & Modular Systems** are tested as individual components or as a whole with the system assembled.
- **Connector Tests** are easily added to any project with ScanDIMM, ScanPCI, and ScanIO modules to increase boundary-scan test coverage.
- **Backplane Testing** is simplified with simple test preparation and automatic mating list generation.
- **Multi-chip Modules (MCM)** can be defined by their internal components, allowing boundary-scan testing System-on-a-Chip (SoC), System-in-a-Package (SIP), and other intra-IC interconnect technologies.

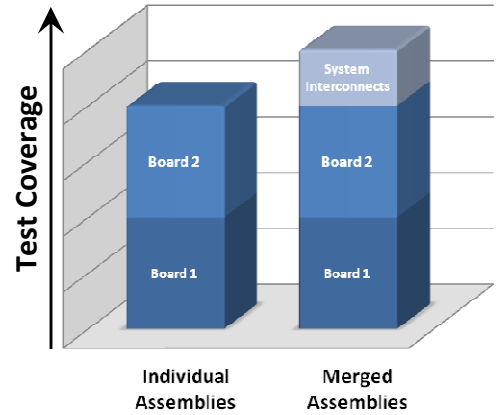
Learn More: For more information about Corelis products, please visit www.corelis.com

The ScanExpress Merge software application facilitates combination and generation of boundary-test test projects for multiple interconnected Units Under Test (UUTs) and external boundary-scan modules. ScanExpress Merge integrates with the ScanExpress TPG test development and generation application to combine test data for multiple assemblies into a single, unified test project.

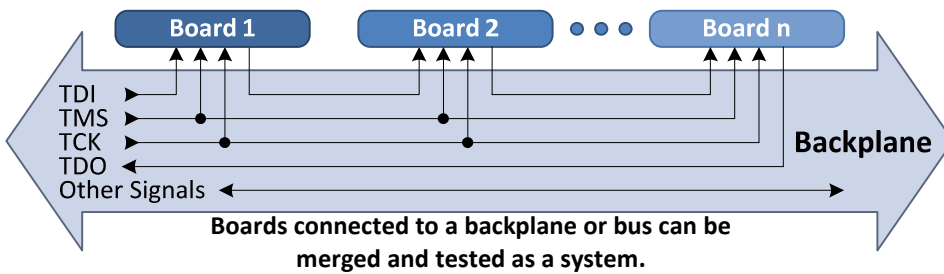
Multiple Target Assemblies

In a typical application, ScanExpress TPG is used to generate tests for each system board independently. After creating the individual tests, ScanExpress Merge combines all test generation files into a single combined file set for testing the complete system, offering increased convenience and additional test coverage.

ScanExpress Merge can be used to combine tests for multiple boards connected by a backplane. By combining tests for the individual boards with interconnection definitions for the backplane, ScanExpress Merge can create a single, unified test for the assembled system.



Combining assembly tests can increase overall boundary-scan test coverage.

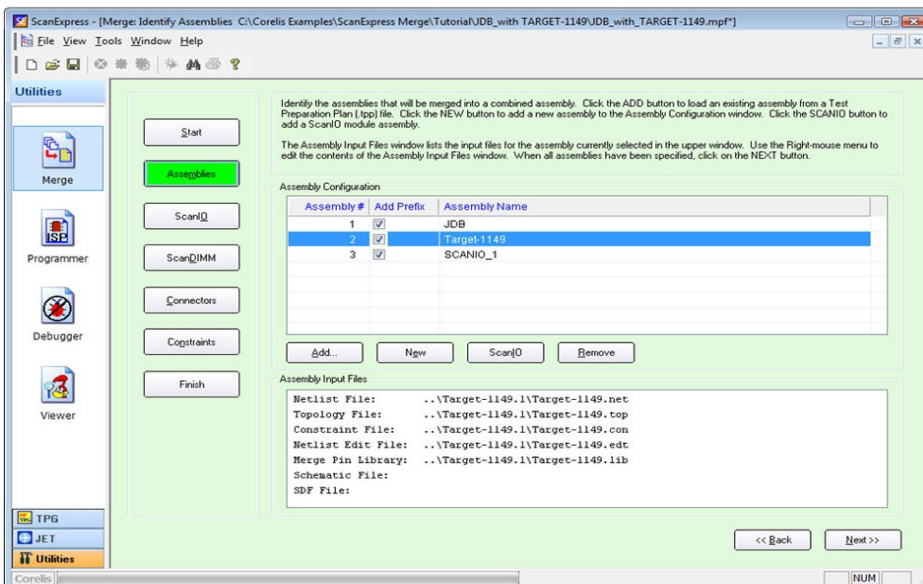


Graphical User Interface

The ScanExpress Merge software application is fully integrated into the ScanExpress TPG development environment. The ScanExpress Merge interactive Graphical User Interface (GUI) guides the user through the process of entering and configuring assemblies in the merge plan. Once all assembly information has been defined, ScanExpress Merge automatically loads the combined project into ScanExpress TPG for further test development and vector generation.

ScanIO Module Integration

ScanExpress Merge automates the process of developing tests for systems that include connections to DIMM memory sockets, PCI slots, and ScanIO connectors. ScanExpress Merge combines the data of the board and the data of the ScanIO, ScanPCI, and ScanDIMM parallel IO modules into a single set of input files for use with the ScanExpress TPG intelligent test pattern generator software. The process is completely automated to save time—no need to manually describe the connections between the PCB connectors and the modules.



ScanExpress Merge Graphical User Interface

Ordering Information

Part Number—20196

For more information, please visit our website at

<http://www.corelis.com/>

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